



# BUK9M24-80L

N-channel 80 V, 24 mOhm logic level MOSFET in LPAK33

3 September 2024

Product data sheet

## 1. General description

Logic level N-channel MOSFET in an LPAK33 (Power33) package using TrenchMOS technology. This product has been designed and qualified to AEC-Q101 standard for use in high performance automotive applications.

## 2. Features and benefits

- Logic-level compatible
- Trench12 MOSFET technology
- Efficient switching with soft body-diode recovery
- Automotive qualified to AEC-Q101 at 175 °C
- Side-wettable flanks for robust solder joints and automatic optical inspection

## 3. Applications

- 12 V, 24 V and 48 V automotive systems
- Motors, lamps and solenoid control
- Transmission control
- LED lighting
- Circuit protection

## 4. Quick reference data

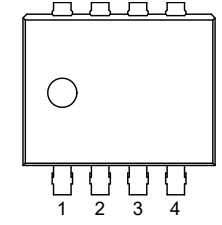
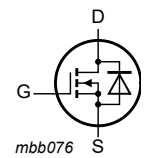
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DS}$	drain-source voltage	$25\text{ °C} \leq T_j \leq 175\text{ °C}$	-	-	80	V
$I_D$	drain current	$V_{GS} = 10\text{ V}; T_{mb} = 25\text{ °C};$ <a href="#">Fig. 2</a>	[1]	-	35	A
$P_{tot}$	total power dissipation	$T_{mb} = 25\text{ °C};$ <a href="#">Fig. 1</a>	-	-	67	W
<b>Static characteristics</b>						
$R_{DSon}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}; I_D = 10\text{ A}; T_j = 25\text{ °C};$ <a href="#">Fig. 11</a>	12.9	19.8	23.6	mΩ
<b>Dynamic characteristics</b>						
$Q_{GD}$	gate-drain charge	$I_D = 10\text{ A}; V_{DS} = 40\text{ V}; V_{GS} = 5\text{ V};$ $T_j = 25\text{ °C};$ <a href="#">Fig. 13</a> ; <a href="#">Fig. 14</a>	0.6	2.1	4.6	nC
<b>Source-drain diode</b>						
$Q_r$	recovered charge	$I_S = 10\text{ A}; di_S/dt = -100\text{ A}/\mu\text{s}; V_{GS} = 0\text{ V};$ $V_{DS} = 40\text{ V}; T_j = 25\text{ °C};$ <a href="#">Fig. 17</a>	-	16	-	nC

[1] 35 A continuous current has been successfully demonstrated during application tests. Practically the current will be limited by PCB, thermal design and operating temperature.

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	 <p>LFPAK33 (SOT1210)</p>	
2	S	source		
3	S	source		
4	G	gate		
mb	D	Mounting base; connected to drain		

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BUK9M24-80L	LFPAK33	Plastic, single ended surface mounted package (LFPAK33); 8 leads; 0.65 mm pitch	SOT1210

## 7. Marking

Table 4. Marking codes

Type number	Marking code
BUK9M24-80L	92480L

## 8. Limiting values

Table 5. Limiting values

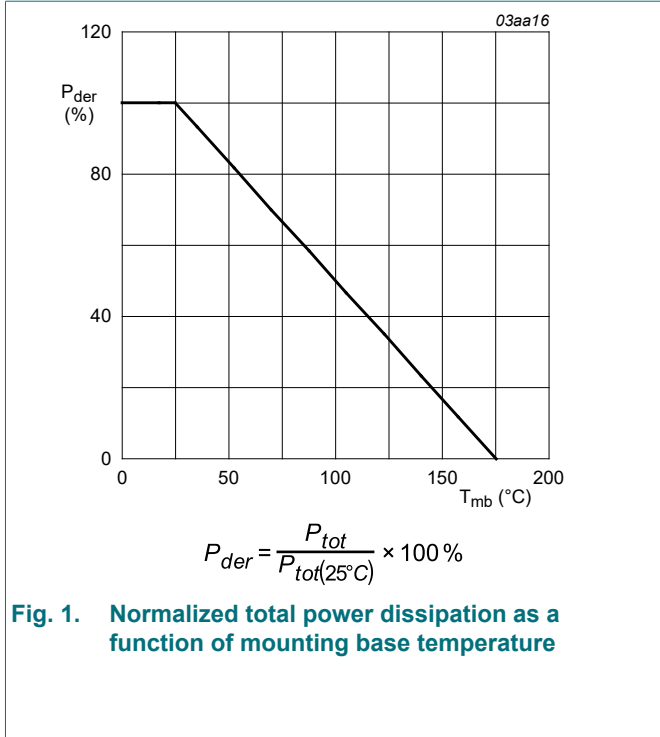
In accordance with the Absolute Maximum Rating System (IEC 60134).  $T_j = 25\text{ °C}$  unless otherwise stated.

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{DS}$	drain-source voltage	$25\text{ °C} \leq T_j \leq 175\text{ °C}$		-	80	V
$V_{GS}$	gate-source voltage			-20	20	V
$P_{tot}$	total power dissipation	$T_{mb} = 25\text{ °C}$ ; Fig. 1		-	67	W
$I_D$	drain current	$V_{GS} = 10\text{ V}$ ; $T_{mb} = 25\text{ °C}$ ; Fig. 2	[1]	-	35	A
		$V_{GS} = 10\text{ V}$ ; $T_{mb} = 100\text{ °C}$ ; Fig. 2		-	25	A
$I_{DM}$	peak drain current	pulsed; $t_p \leq 10\text{ }\mu\text{s}$ ; $T_{mb} = 25\text{ °C}$ ; Fig. 3		-	141	A
$T_{stg}$	storage temperature			-55	175	°C
$T_j$	junction temperature			-55	175	°C
<b>Source-drain diode</b>						
$I_S$	source current	$T_{mb} = 25\text{ °C}$		-	35	A
$I_{SM}$	peak source current	pulsed; $t_p \leq 10\text{ }\mu\text{s}$ ; $T_{mb} = 25\text{ °C}$		-	141	A
<b>Avalanche ruggedness</b>						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$I_D = 16\text{ A}$ ; $V_{sup} \leq 80\text{ V}$ ; $R_{GS} = 50\text{ }\Omega$ ; $V_{GS} = 10\text{ V}$ ; $T_{j(init)} = 25\text{ °C}$ ; unclamped; $t_{AL} = 37\text{ }\mu\text{s}$ ; Fig. 4	[2] [3]	-	30.7	mJ

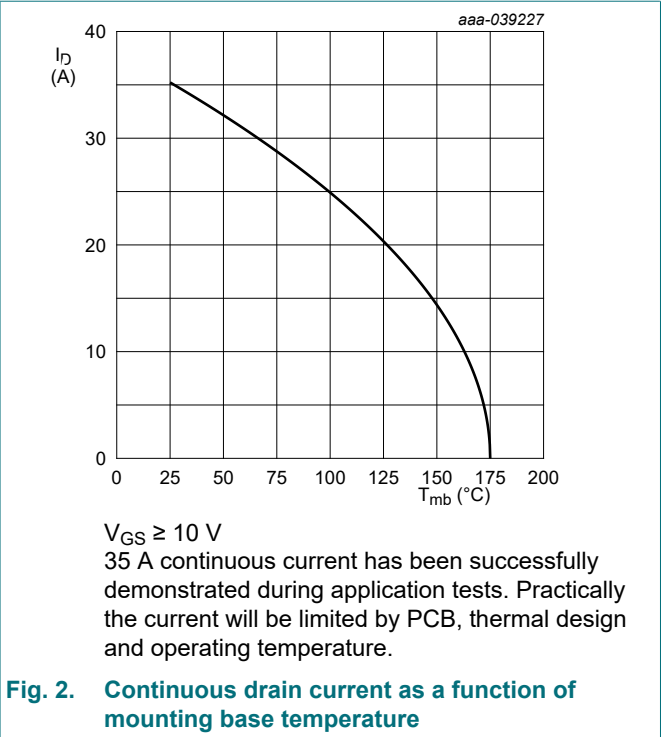
N-channel 80 V, 24 mOhm logic level MOSFET in LFPAK33

Symbol	Parameter	Conditions		Min	Max	Unit
I <sub>AS</sub>	non-repetitive avalanche current	V <sub>sup</sub> = 80 V; V <sub>GS</sub> = 10 V; T <sub>j(init)</sub> = 25 °C; R <sub>GS</sub> = 50 Ω; Fig. 4	[2] [3]	-	16	A

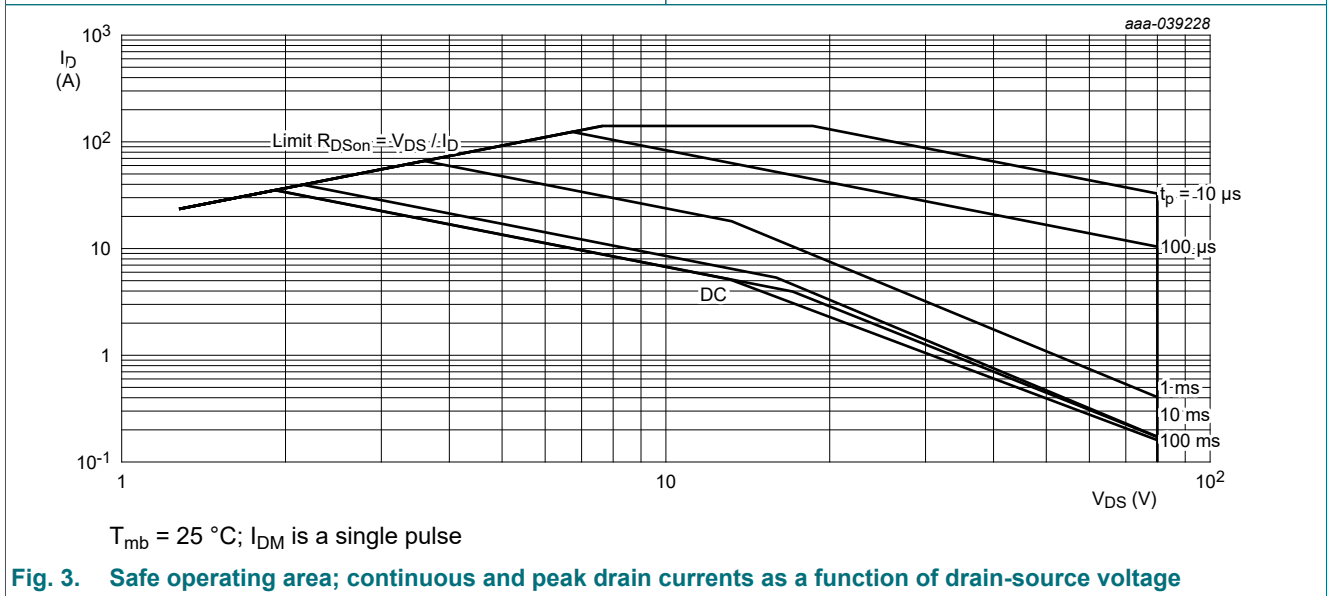
- [1] 35 A continuous current has been successfully demonstrated during application tests. Practically the current will be limited by PCB, thermal design and operating temperature.
- [2] Single-pulse avalanche rating limited by maximum junction temperature of 175 °C.
- [3] Refer to application note AN10273 for further information.



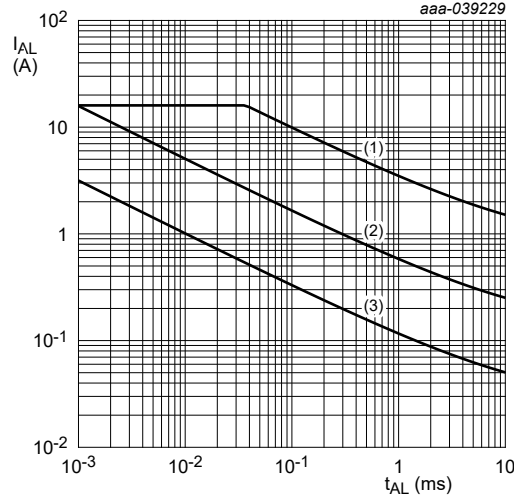
**Fig. 1. Normalized total power dissipation as a function of mounting base temperature**



**Fig. 2. Continuous drain current as a function of mounting base temperature**



**Fig. 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage**



(1)  $T_{j\text{ (init)}} = 25\text{ °C}$ ; (2)  $T_{j\text{ (init)}} = 150\text{ °C}$ ; (3) Repetitive Avalanche

Fig. 4. Avalanche rating; avalanche current as a function of avalanche time

### 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 5	-	2	2.23	K/W

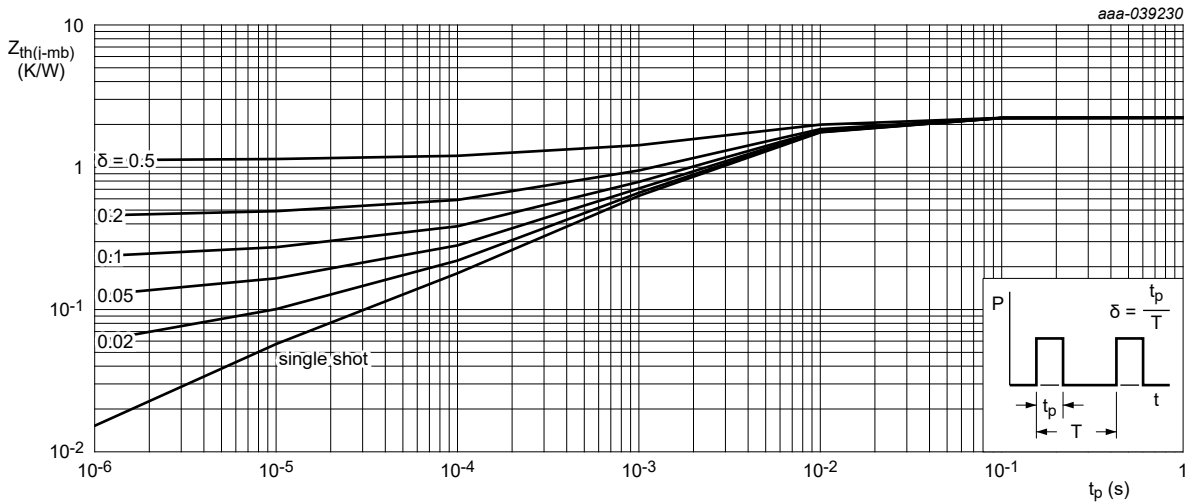


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

## 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu A; V_{GS} = 0 V; T_j = 25 \text{ }^\circ C$	80	91	-	V
		$I_D = 250 \mu A; V_{GS} = 0 V; T_j = -40 \text{ }^\circ C$	73.5	88.5	-	V
		$I_D = 250 \mu A; V_{GS} = 0 V; T_j = -55 \text{ }^\circ C$	72	87	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 0.06 \text{ mA}; V_{DS}=V_{GS}; T_j = 25 \text{ }^\circ C;$ <a href="#">Fig. 9; Fig. 10</a>	1.4	1.7	2.05	V
		$I_D = 0.06 \text{ mA}; V_{DS}=V_{GS}; T_j = 175 \text{ }^\circ C;$ <a href="#">Fig. 10</a>	0.5	-	-	V
		$I_D = 0.06 \text{ mA}; V_{DS}=V_{GS}; T_j = -55 \text{ }^\circ C;$ <a href="#">Fig. 10</a>	-	-	2.45	V
$I_{DSS}$	drain leakage current	$V_{DS} = 80 V; V_{GS} = 0 V; T_j = 25 \text{ }^\circ C$	-	0.01	1	$\mu A$
		$V_{DS} = 80 V; V_{GS} = 0 V; T_j = 125 \text{ }^\circ C$	-	3.2	100	$\mu A$
		$V_{DS} = 80 V; V_{GS} = 0 V; T_j = 175 \text{ }^\circ C$	-	34	500	$\mu A$
$I_{GSS}$	gate leakage current	$V_{GS} = 20 V; V_{DS} = 0 V; T_j = 25 \text{ }^\circ C$	-	2	100	nA
		$V_{GS} = -20 V; V_{DS} = 0 V; T_j = 25 \text{ }^\circ C$	-	2	100	nA
$R_{DSon}$	drain-source on-state resistance	$V_{GS} = 10 V; I_D = 10 A; T_j = 25 \text{ }^\circ C;$ <a href="#">Fig. 11</a>	12.9	19.8	23.6	m $\Omega$
		$V_{GS} = 10 V; I_D = 10 A; T_j = 105 \text{ }^\circ C;$ <a href="#">Fig. 12</a>	19	30.5	38	m $\Omega$
		$V_{GS} = 10 V; I_D = 10 A; T_j = 125 \text{ }^\circ C;$ <a href="#">Fig. 12</a>	20.7	33.5	42	m $\Omega$
		$V_{GS} = 10 V; I_D = 10 A; T_j = 175 \text{ }^\circ C;$ <a href="#">Fig. 12</a>	25.2	42	54	m $\Omega$
		$V_{GS} = 4.5 V; I_D = 10 A; T_j = 25 \text{ }^\circ C;$ <a href="#">Fig. 11</a>	16.5	27	35.5	m $\Omega$
		$V_{GS} = 4.5 V; I_D = 10 A; T_j = 105 \text{ }^\circ C;$ <a href="#">Fig. 12</a>	24.2	41	57	m $\Omega$
		$V_{GS} = 4.5 V; I_D = 10 A; T_j = 125 \text{ }^\circ C;$ <a href="#">Fig. 12</a>	26.5	45	63.1	m $\Omega$
		$V_{GS} = 4.5 V; I_D = 10 A; T_j = 175 \text{ }^\circ C;$ <a href="#">Fig. 12</a>	32.2	55	81.2	m $\Omega$
$R_G$	gate resistance	$f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ C$	0.8	1.7	3.4	$\Omega$
<b>Dynamic characteristics</b>						
$Q_{G(tot)}$	total gate charge	$I_D = 10 A; V_{DS} = 40 V; V_{GS} = 5 V;$ $T_j = 25 \text{ }^\circ C;$ <a href="#">Fig. 13; Fig. 14</a>	4.8	9.6	14.4	nC
		$I_D = 10 A; V_{DS} = 40 V; V_{GS} = 10 V;$ $T_j = 25 \text{ }^\circ C;$ <a href="#">Fig. 13; Fig. 14</a>	9.4	18.9	28.4	nC
$Q_{GS}$	gate-source charge	$I_D = 10 A; V_{DS} = 40 V; V_{GS} = 5 V;$ $T_j = 25 \text{ }^\circ C;$ <a href="#">Fig. 13; Fig. 14</a>	2.2	3.7	5.2	nC
$Q_{GD}$	gate-drain charge	$I_D = 10 A; V_{DS} = 40 V; V_{GS} = 5 V;$ $T_j = 25 \text{ }^\circ C;$ <a href="#">Fig. 13; Fig. 14</a>	0.6	2.1	4.6	nC
$V_{GS(pl)}$	gate-source plateau voltage	$I_D = 10 A; V_{DS} = 40 V; T_j = 25 \text{ }^\circ C;$ <a href="#">Fig. 13; Fig. 14</a>	-	3	-	V
$C_{iss}$	input capacitance	$V_{DS} = 25 V; V_{GS} = 0 V; f = 1 \text{ MHz};$ $T_j = 25 \text{ }^\circ C;$ <a href="#">Fig. 15</a>	775.8	1293	1810	pF
$C_{oss}$	output capacitance	$V_{DS} = 25 V; V_{GS} = 0 V; f = 1 \text{ MHz};$ $T_j = 25 \text{ }^\circ C;$ <a href="#">Fig. 15</a>	195	325	520	pF
$C_{rss}$	reverse transfer capacitance	$V_{DS} = 25 V; V_{GS} = 0 V; f = 1 \text{ MHz};$ $T_j = 25 \text{ }^\circ C;$ <a href="#">Fig. 15</a>	9.2	23	36.8	pF

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$t_{d(on)}$	turn-on delay time	$V_{DS} = 40\text{ V}; R_L = 4\ \Omega; V_{GS} = 5\text{ V};$ $R_{G(ext)} = 5\ \Omega; T_j = 25\text{ }^\circ\text{C}$	-	9.1	-	ns
$t_r$	rise time		-	7.7	-	ns
$t_{d(off)}$	turn-off delay time		-	12.3	-	ns
$t_f$	fall time		-	6.1	-	ns
<b>Source-drain diode</b>						
$V_{SD}$	source-drain voltage	$I_S = 15\text{ A}; V_{GS} = 0\text{ V}; T_j = 25\text{ }^\circ\text{C};$ Fig. 16	-	0.88	1	V
$t_{rr}$	reverse recovery time	$I_S = 10\text{ A}; di_S/dt = -100\text{ A}/\mu\text{s}; V_{GS} = 0\text{ V};$	-	28	-	ns
$Q_r$	recovered charge	$V_{DS} = 40\text{ V}; T_j = 25\text{ }^\circ\text{C};$ Fig. 17	-	16	-	nC

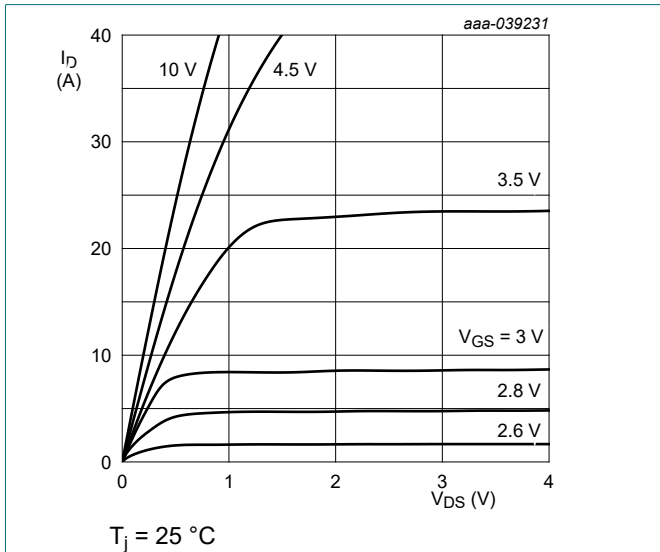


Fig. 6. Output characteristics; drain current as a function of drain-source voltage; typical values

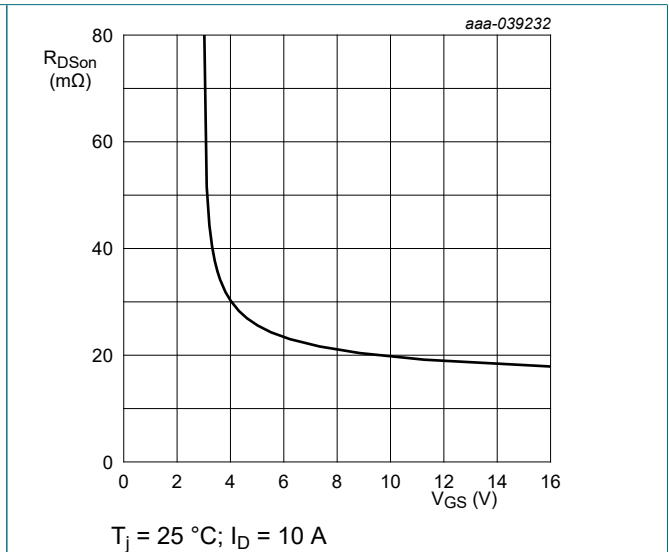


Fig. 7. Drain-source on-state resistance as a function of gate-source voltage; typical values

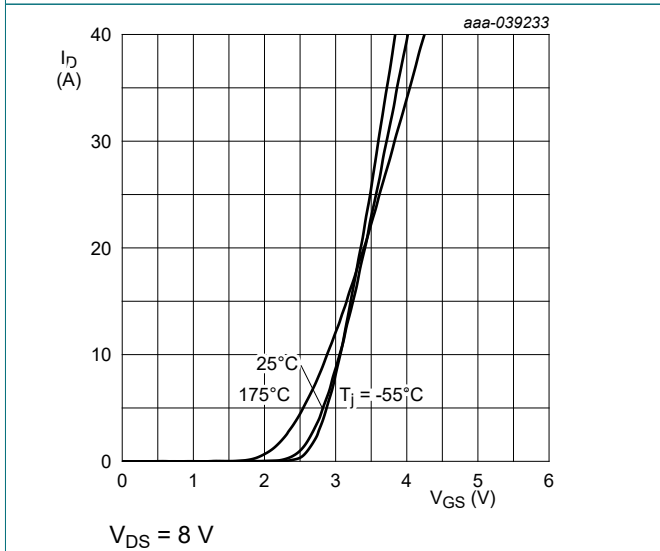


Fig. 8. Transfer characteristics; drain current as a function of gate-source voltage; typical values

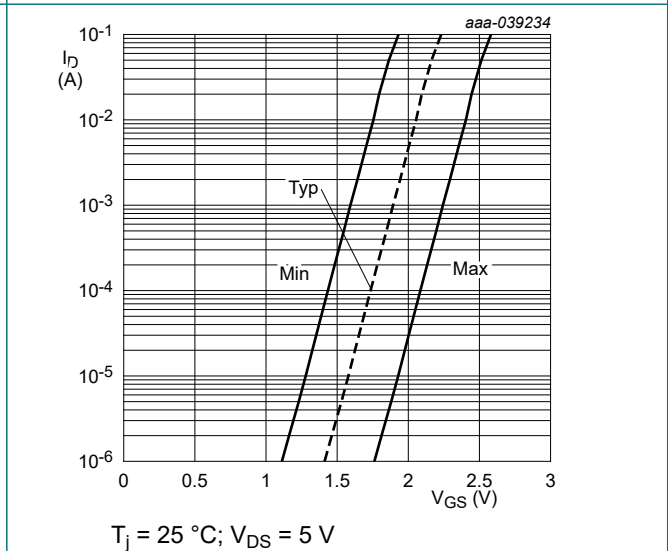


Fig. 9. Sub-threshold drain current as a function of gate-source voltage

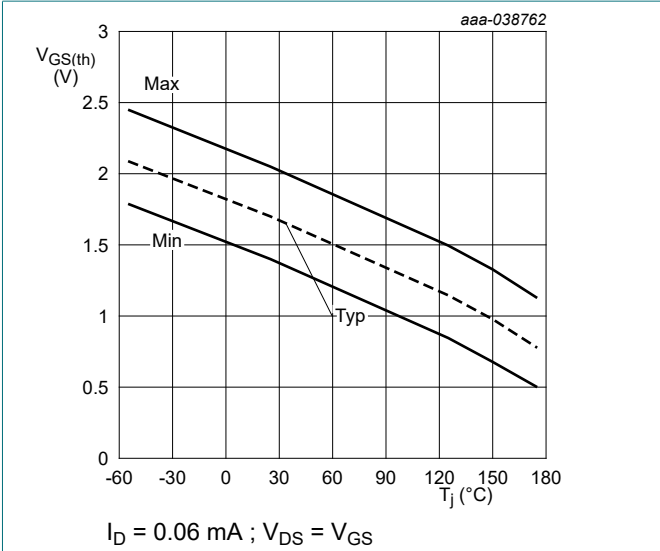


Fig. 10. Gate-source threshold voltage as a function of junction temperature

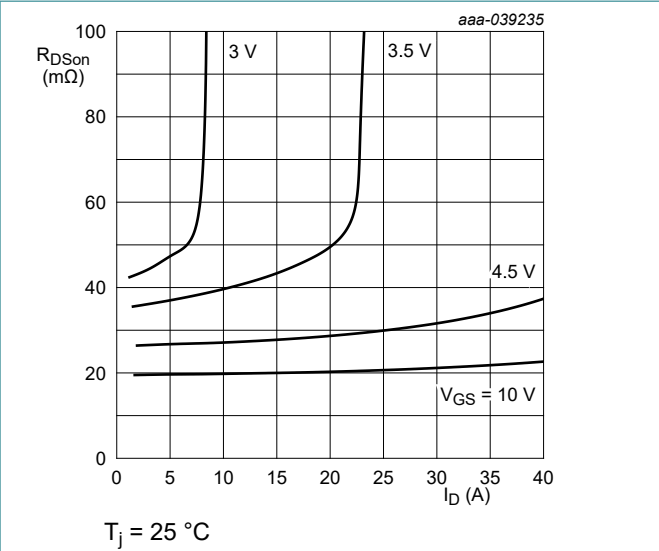


Fig. 11. Drain-source on-state resistance as a function of drain current; typical values

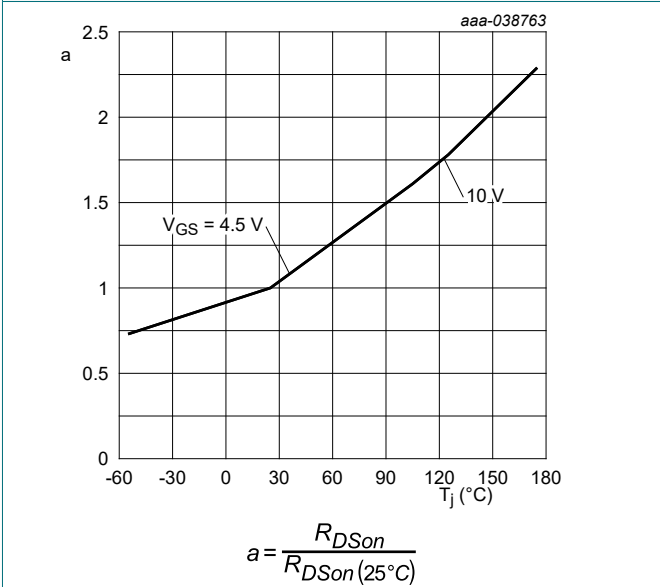


Fig. 12. Normalized drain-source on-state resistance factor as a function of junction temperature

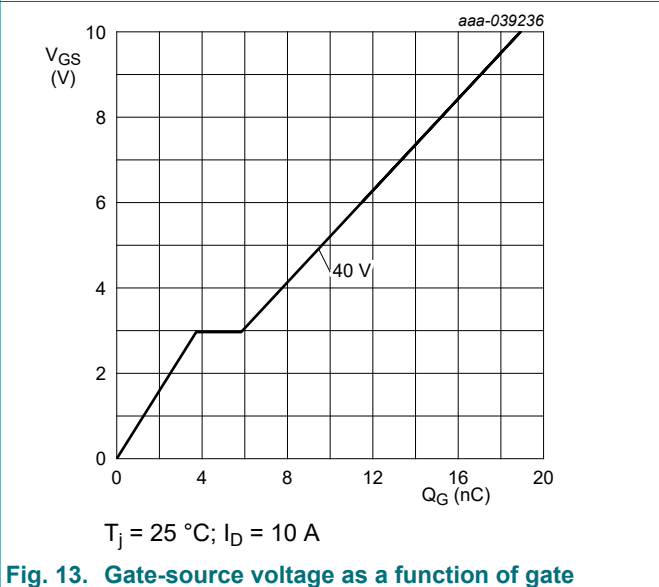
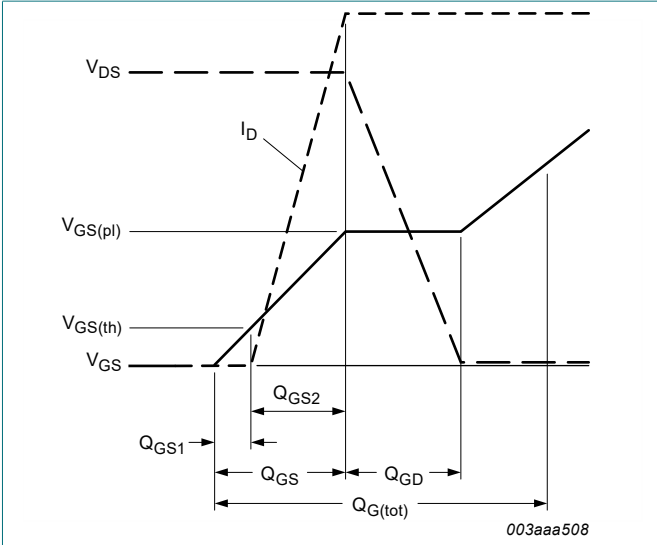
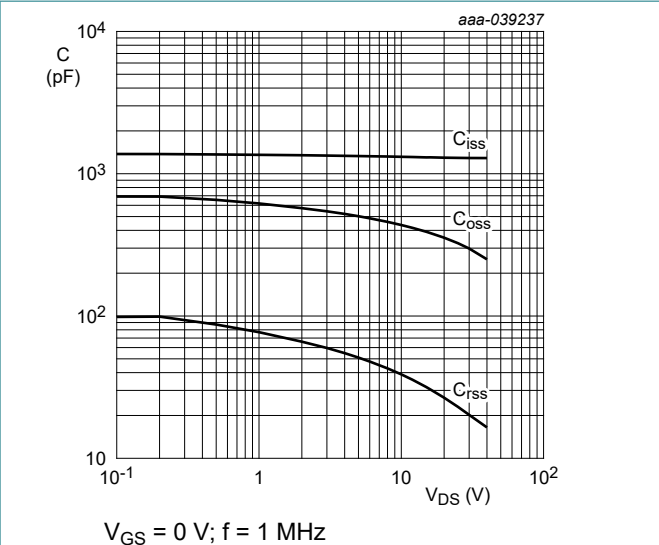


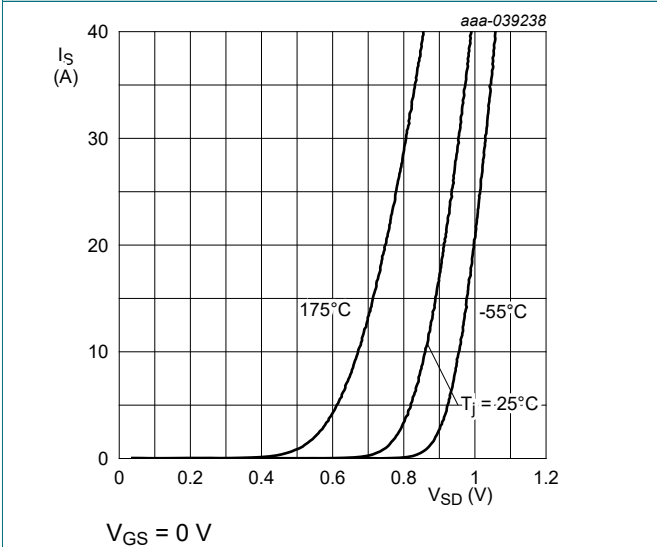
Fig. 13. Gate-source voltage as a function of gate charge; typical values



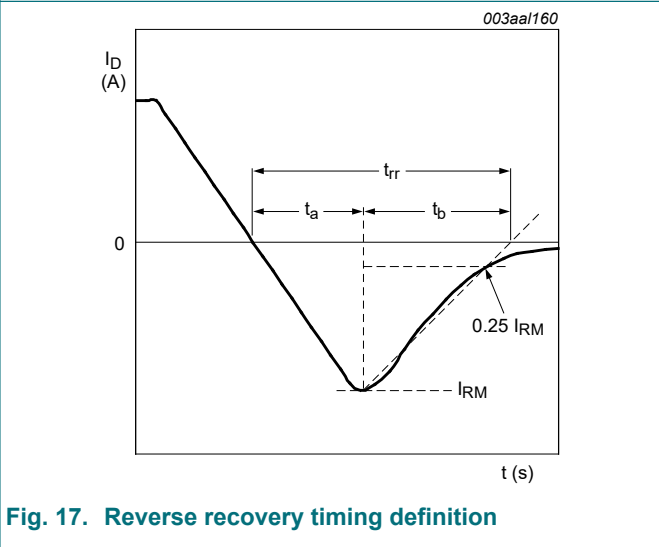
**Fig. 14. Gate charge waveform definitions**



**Fig. 15. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values**



**Fig. 16. Source-drain (diode forward) current as a function of source-drain (diode forward) voltage; typical values**



**Fig. 17. Reverse recovery timing definition**



### 11. Package outline

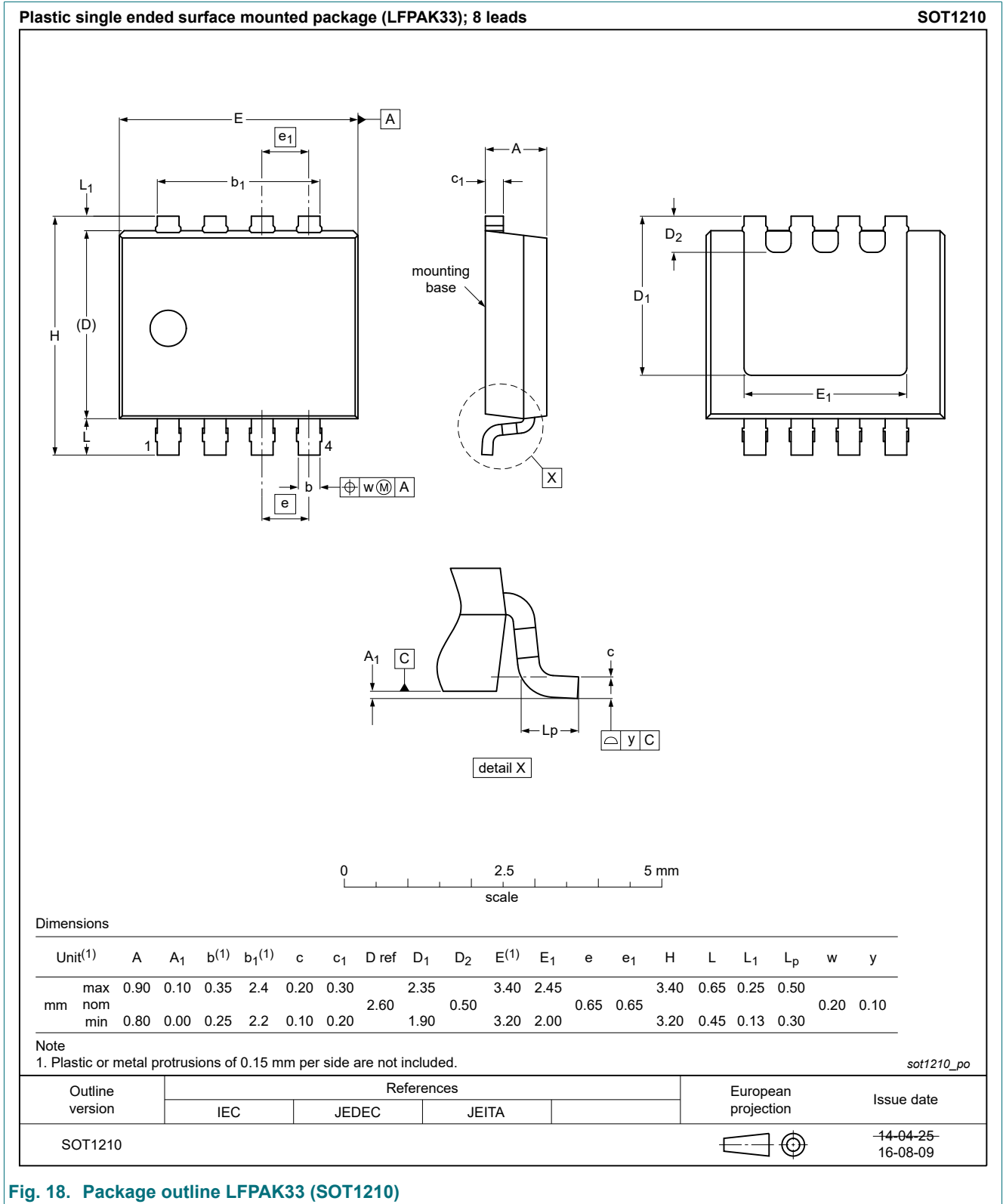
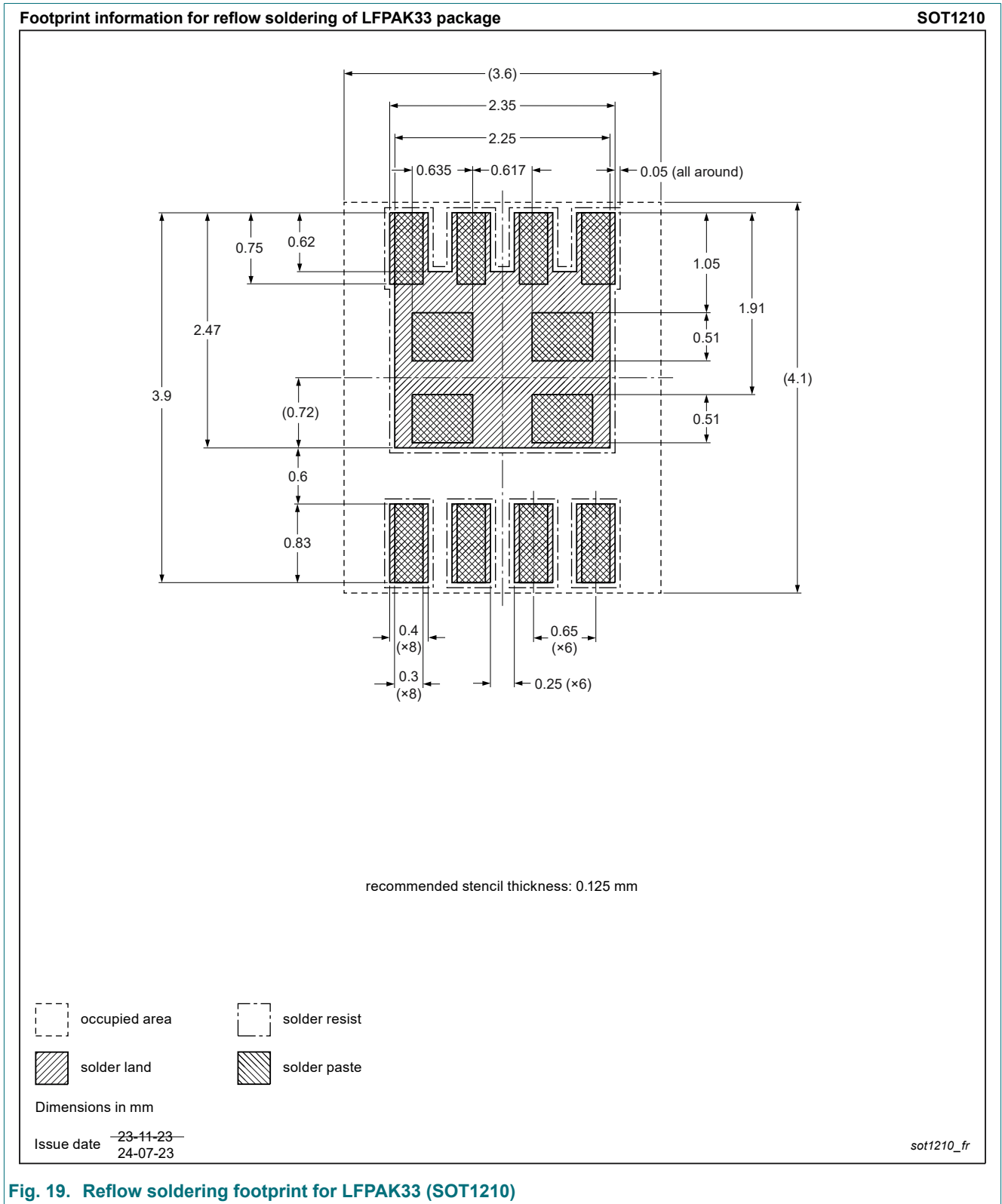


Fig. 18. Package outline LPAK33 (SOT1210)

## 12. Soldering



**Fig. 19. Reflow soldering footprint for LFPAK33 (SOT1210)**

## 13. Legal information

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Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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## Contents

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- 1. General description..... 1
- 2. Features and benefits..... 1
- 3. Applications..... 1
- 4. Quick reference data..... 1
- 5. Pinning information.....2
- 6. Ordering information.....2
- 7. Marking.....2
- 8. Limiting values..... 2
- 9. Thermal characteristics..... 4
- 10. Characteristics.....5
- 11. Package outline..... 9
- 12. Soldering..... 10
- 13. Legal information.....11

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